



## Product Change Notification: CAAN-02APAB836

### Date:

13-Dec-2024

### Product Category:

Memory

### Notification Subject:

CCB 6571 Final Notice: Qualification of NSEB and UTL3 as additional assembly sites for SST26VF064B-104I/MN, SST26VF064B-104V/MN, SST26VF064BT-104V/MN and SST26VF064BT-104I/MN catalog part numbers (CPN) available in 8L TDFN (6x8x0.8mm) package.

### Affected CPNs:

[\*\*CAAN-02APAB836\\_Affected\\_CPN\\_12132024.pdf\*\*](#)

[\*\*CAAN-02APAB836\\_Affected\\_CPN\\_12132024.csv\*\*](#)

### Notification Text:

**PCN Status:**Final Notification

**PCN Type:**Manufacturing Change

**Microchip Parts Affected:**Please open one of the files found in the Affected CPNs section.  
Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

**Description of Change:**Qualification of NSEB and UTL3 as additional assembly sites for SST26VF064B-104I/MN, SST26VF064B-104V/MN, SST26VF064BT-104V/MN and SST26VF064BT-104I/MN catalog part numbers (CPN) available in 8L TDFN (6x8x0.8mm) package.

### Pre and Post Change Summary:

	Pre Change	Post Change

Assembly Site	Lingsen Precision Industries, LTD. (LPI)	Lingsen Precision Industries, LTD. (LPI)	UTAC Thai Limited (UTL-1) LTD. (NSEB)	UTAC Thai Limited (UTL-3) (UTL3)
Wire Material	Au	Au	CuPdAu	CuPdAu
Die Attach Material	8340	8340	558-2C31	558-2C31
Molding Compound Material	G770HT	G770HT	G700LTD	G700LTD
Lead-Frame Material	C194	C194	C194	C194
Lead-Frame Paddle Size	256X201 mils	256X201 mils	256X201 mils	256X201 mils
Lead-Frame Lead-Lock Design	No	No	Yes	Yes
DAP Surface Prep	Ag on lead	Ag Spot Plating	Ag on lead	Ag on lead only

**Impacts to Data Sheet:**None

**Change Impact:**None

**Reason for Change:**To improve on-time delivery performance by qualifying NSEB and UTL3 as additional assembly sites.

**Change Implementation Status:**In Progress

**Estimated First Ship Date:**December 31, 2024 (date code: 2453)

Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

**Time Table Summary:**

	October 2023	>	December 2024
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Workweek	40	41	42	43	44		49	50	51	52	53
Initial PCN Issue Date	X										
Qual Report Availability							X				
Final PCN Issue Date							X				
Estimated Implementation Date										X	

**Method to Identify Change:**Traceability code

**Qualification Report:**Please open the attachments included with this PCN labeled as PCN\_#\_Qual\_Report.

**Revision History:**October 05, 2023: Issued initial notification.

December 05, 2024: Issued final notification. Attached Qualification Report. Provided estimated first ship date to be on December 31, 2024.

December 13, 2024: Re-issued final notification to update the time table summary and date code.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

## Attachments:

[\*\*PCN\\_Caan-02APAB836\\_Pre and Post Change Summary.pdf\*\*](#)

[\*\*PCN\\_Caan-02APAB836\\_Qual Report.pdf\*\*](#)

Please contact your local **Microchip sales office** with questions or concerns regarding this notification.

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